ABSTRACT

A module component is provided having a sufficient shield effect and fabricated low in height.

On a circuit board (10), a mount device (30) comprising an electronic part is mounted, and this mount device (30) is sealed with a sealing body (40). On the surface of this sealing body (40), a metal film (20) is formed. A ground pattern (50) is formed at the outer periphery of the principal surface of the circuit board (10), and a configuration is formed in which said metal film (20) is conductively connected with the ground pattern (50).



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